

## TABLE OF CONTENTS

<i>Preface</i>	iii
<i>Conference Organization</i>	iv
Section I	
<b>High Density Packaging and Related Technologies</b>	<b>1</b>
1 Applications of Electrochemistry to Chip Packaging, an Overview* <i>Z. Kovac</i>	3
2 Micro-Fabrication Technologies on Recent Packagings* <i>T. Kobayashi and H. Honma</i>	11
3 Microfabrication on Electronics Packaging* <i>S.-I. Wakabayashi</i>	21
4 Electrochemically Deposited Microstructures in Packaging and System Integration* <i>G. Engelmann, J. Wolf, L. Dietrich, S. Fehlberg, S. Müller, O. Ehrmann and H. Reichl</i>	31
5 Recent Advances in Gap Filling Cu Electroplating Technology* <i>M. Zhu, D. Papapanayiotou, Y. Lee, and C. H. Ting</i>	38
6 Tin-Silver Alloys for Flip-Chip Bonding Studied with a Rotating Cylinder Electrode <i>P. T. Tang, E.H. Pedersen, G. Bech-Nielsen, and J.F. Kuhmann</i>	44
7 Via-Filling Using Electroplating for Build-Up Printed Circuit Boards <i>J. Kawasaki, K. Mihara, T. Kobayashi, and H. Honma</i>	51
8 Improvements of Plating Copper Distribution into Printed Circuit Board Interconnections <i>J. Fournier, R. Menini, and Y.M. Henuset</i>	56
Section II	
<b>Electronic Devices and Related Materials / Processes</b>	<b>69</b>
9 Integration of Electroless and Electrolytic Cu in the IC Back End of Line Technologies* <i>K. Maex, S.H. Brongersma, Y. Lantasov, E. Richard, R. Palmans and I. Vervoort</i>	71
10 What Can Electrochemistry Do for the Development of Molecular Electronics? Use of Ultrathin Films of Polythiophene for Device Preparation* <i>W. Plieth</i>	80
11 Infrared Spectroscopy of Silicon Oxide Layer Formed on Silicon Substrate <i>J. Fujikawa, H. Ohta, A. Sakai, and K. Fujikawa</i>	89
12 Induced Codeposition of Trace Metals on H-Si(111) Surface in Buffered Fluoride Solutions <i>T. Homma, J. Tsukano, and T. Osaka</i>	95
13 Material Properties of Electroless 100-200 nm Thick CoWP Films <i>Y. Shacham-Diamand, Y. Sverdlov, N. Petrov, L. Zhou, N. Croitoru, A. Inberg, E. Gileadi, A. Kohn, and M. Eizenberg</i>	102

14 A Sequential Copper Plating Process for Multiple Feature Sizes for HDI Applications <i>J.J. Sun, E.J. Taylor, and M.E. Inman</i>	111
15 Formation of Passivation Layer by Electrophoresis of Polyimide <i>M. Y. Lim and T. C. Chou</i>	120
16 Recent Topics in Electroplated Hard Gold and Alternatives for Electrical Contact Applications* <i>Y. Okinaka and T. Homma</i>	132
17 Electrodeposition of Gold from a Sulphite Bath by Direct and Pulse Currents: Applications to Opto-Electronic Devices* <i>S. Roy and S. Caprodossi</i>	145
 Section III	
<b>MEMS / Microfabrations and Related Technologies</b>	157
18 Electroless Deposition in Microelectronics: New Trends* <i>E. J. O'Sullivan</i>	159
19 Electroless Deposition of Silver and Silver-Tungsten Films for Microelectronics and MEMS Applications* <i>Y. Shacham-Diamand, A. Inberg, Y. Sverdlov, and N. Croitoru</i>	172
20 Patterned Channel-Constrained Metallization of Alumina and Diamond Substrates* W.J. Dressick, C. S. Dulcey, S. L. Brandow, M-S. Chen, D. L. Leonard, J.M. Calvert, and C. W. Sims	179
21 Electrochemical Studies on Etching of Micro-Electromechanical Systems (MEMS) Materials in Tetramethyl Ammonium Hydroxide (TMAH) Solutions: A Review <i>V. S. Donepudi and J. R. Selman</i>	188
22 Fabrication of Electroplated Nickel Micromechanical Comb Resonators <i>J. T. Ravnkilde, A. D. Yalçinkaya, L. S. Johansen, and O. Hansen</i>	197
23 Long-Scale Ordered Nano-Patterns Formed by Electrochemical Polishing and Anodization of Polycrystalline and Single Crystal Aluminum <i>V. Konovalov, R. M. Metzger, and G. Zangari</i>	203
24 Galvanic Modifications of Multifunctional Silicon-Based Microelectrode Arrays <i>G. Buss, H. Ecken, S. Winkels, M. J. Schöning, H. Lüth, and J.W. Schultze</i>	209
25 Electroless Metallization of MEMS Nanostructures <i>S. Lopatin, N. MacDonald, J. Chen, and S. Adams</i>	216
 Section IV	
<b>Magnetic Materials and Devices</b>	227
26 Microstructure and Low-Field Magnetoresistance of La-Sr-Mn-O Thin Films* <i>K-K. Choi, T. Taniyama, and Y. Yamazaki</i>	229
27 Magnetic and Magnetoresistive Properties of Electrodeposited Cu-Co Multilayers* <i>E. Chassaing, A. Morrone, and J. Schmidt</i>	235

28 Purity of Films and Performance of Recording Heads*	
<i>K. Ohashi, M. Saito, H. Honjo, T. Toba, Y. Nonaka and N. Ishiwata</i>	241
29 Computer-Controlled Pulse-Plating of Alloys*	
<i>I. Kazeminezhad and W. Schwarzacher</i>	250
30 Electrodeposited Co-Fe Based Alloy Films for High Moment Magnetic Recording Write Heads	
<i>X. Liu, P. Evans, and G. Zangari</i>	255
31 Preparation and Characterization of Electrodeposited High-Bs CoNiFe Thin Films with High Resistivity and Improvement of Their Corrosion Resistance	
<i>M. Kaseda, M. Yamada, T. Nakanishi, and T. Osaka</i>	263
32 Challenge to a Physical Limit in Longitudinal High Density Recording Media*	
<i>M. Takahashi, H. Shoji, S. Yoshimura, D. D. Djayaprawira</i>	273
33 New Proposal of High Density Magnetic Recording Media for Next Generation*	
<i>T. Osaka and T. Onoue</i>	286
34 Microstructure and Magnetic Behavior of Granular CoPt Thin Film*	
<i>N. Hiratsuka, K. Akiyoshi, K. Kakizaki, D. M. Donnet, and K. Kobayashi</i>	298
35 Effect of a Paramagnetic CoCr40 Intermediate Layer on Magnetic Properties and Crystalline Structure of the CoCr <sub>18</sub> Pt <sub>6</sub> Ta <sub>3</sub> Perpendicular Magnetic Recording Medium with an Amorphous C Underlayer	
<i>T. Asahi, T. Onoue, A. Takizawa, and T. Osaka</i>	304

## Section V

### Fundamental Studies on the Materials for Electrochemical Technology Applications 315

36 Novel Agitation for PCB Production: Use of Eductor Technology*	
<i>M. Ward, D. R. Gabe, and J. N. Crosby</i>	317
37 Copper Plating from Citrate Baths: The Role of Complexation Chemistry*	
<i>C. Henninot, C. Vallières, S. Rode, and M. Matlosz</i>	333
38 The Influence of Additives on the Room-Temperature Recrystallization of Electrodeposited Copper*	
<i>G. R. Stafford, M. D. Vaudin, T. P. Moffat, N. Armstrong, V. D. Jovic and D. R. Kelley</i>	340
39 Effect of Gravitational Level on Morphological Variation Accompanying Electrochemical Etching of Copper	
<i>Y. Konishi, Y. Fukunaka, K. Tsukada, K. Hanasaki, S. Kikuchi, and K. Kurabayashi</i>	351
40 Electrodeposition of Sn-Ag Alloys from Baths Containing Suspended Ag Nanoparticles	
<i>Y. Fujiwara, Y. Yarimizu, H. Enomoto, T. Narahara, and K. Funada</i>	363
41 Electrochemical Deposition of Copper in the Presence of DPS-Brightener and PEG-Leveler	
<i>I. Tabakovic, S. Riemer, T. Baresh, P. Jallen, and M. Alodan</i>	370
42 Nanocomposite Multilayers and Alloy Coatings by Noble Vacuum Arc Discharge	
<i>S. Y. Chun, A. Chayahara, and Y. Horino</i>	380

43 Phosphite Control on Electroless Nickel Plating <i>F. Matsui, S. Kawasaki, and H. Inagawa</i>	386
44 Epitaxial Growth of Zinc Oxide Film by Photo-Induced Chemical Deposition <i>M. Izaki, Y. Kobayashi, J. Katayama, H. Takahashi, H. Nakamura</i>	390
45 Evaluation of Functional Groups and Electrochemical Properties of Plasma-Treated Active Carbon Fiber Electrode for Electric Double-Layer Capacitor <i>K. Okajima, K. Ohta, T. Kondoh, and M. Sudoh</i>	395
46 Photovoltaic Electrodeposition Method and Its Application to Color Filter <i>S. Ohtsu, E. Akutsu, K. Shimizu, and L. S. Pu</i>	405
47 Reflecting on Electrocristallization Research Towards Surface Technology* (1999 Electrochemical Society Research Award of the Electrodeposition Division) <i>R. Winand</i>	411

**Section VI**

<b>Author Index and Key Word Index</b>	427
Author Index	428
Key Word Index	431

\* Invited paper